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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Bayan et al.

Attorney Docket No.:
NSC1P274/P05649

Patent: 7,102,209 B1

Issued: September 5, 2006

Title: SUBSTRATES FOR USE IN
SEMICONDUCTOR MANUFACTURING AND
METHOD OF MAKING SAME**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail on July 19, 2007 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: _____

Aurelia M. Sanchez

**REQUEST FOR CERTIFICATE OF CORRECTION
OF OFFICE MISTAKE
(35 U.S.C. §254, 37 CFR §1.322)**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
Attn: Certificate of Correction

Certificate

JUL 25 2007

of Correction

Dear Sir:

Attached is Form PTO-1050 (Certificate of Correction) at least one copy of which is suitable for printing. The errors together with the exact page and line number where the errors are shown correctly in the application file are as follows:

SPECIFICATION:

1. Column 6, line 45, change "fomls" to --forms--. This appears correctly in the patent application as filed on August 27, 2003, on page 11, paragraph 30, line 6.

JUL 30 2007

Patentee hereby requests expedited issuance of the Certificate of Correction because the error lies with the Office and because the error is clearly disclosed in the records of the Office. As required for expedited issuance, enclosed is documentation that unequivocally supports the patentee's assertion without needing reference to the patent file wrapper.

It is noted that the above-identified errors were printing errors that apparently occurred during the printing process. Accordingly, it is believed that no fees are due in connection with the filing of this Request for Certificate of Correction. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. NSC1P274).

Respectfully submitted,
BEYER WEAVER LLP



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NOV 30 2007

into the spaces 162. However, it is often preferable to use the same material for both the dielectric material 164 and molded cap 125. In other words, the first layer and second layer of dielectric material should often be made of the same material. For example, both layers could be fabricated from a standard molding compound used in forming an IC package, such as Bi-Phenyl Base compound. This minimizes any mechanical stresses that may arise during heating or cooling, should the two layers be made of different materials with different thermal expansion properties.

[0030] The foregoing description, for purposes of explanation, uses specific nomenclature to provide a thorough understanding of the invention. However, it will be apparent to one skilled in the art that the specific details are not required in order to practice the invention. Thus, the foregoing descriptions of specific embodiments of the present invention are presented for purposes of illustration and description. They are not intended to be exhaustive or to limit the invention to the precise forms disclosed. Obviously many modifications and variations are possible in view of the above teachings. For example, while certain embodiments of the invention offer advantages in the formation of LLPs, the invention also includes embodiments that confer benefits to other IC package configurations. The embodiments were chosen and described in order to best explain the principles of the invention and its practical applications, to thereby enable others skilled in the art to best utilize the invention and various embodiments with various modifications as are suited to the particular use contemplated. It is intended that the scope of the invention be defined by the following claims and their equivalents.

(Also Form PT-1050)

UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO. : 7,102,209 B1

Page 1 of 1

DATED : September 5, 2006

INVENTOR(S) : Bayan et al.

It is certified that error appears in the above-identified patent and that said Letters Patent are hereby corrected as shown below:

In the Specification:

Column 6, line 45, change "fomls" to --forms--.

MAILING ADDRESS OF SENDER:

PATENT NO. 7,102,209 B1

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Burden Hour Statement: This form is estimated to take 1.0 hour to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.

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